

Search Notes

Application No.

10/621,576

Examiner

Stephen W. Smoot

Applicant(s)

YOO ET AL.

Art Unit

2813

SEARCHED

Class	Subclass	Date	Examiner
438	108	8/5/2004	SWS
438	113	8/5/2004	SWS
438	114	8/5/2004	SWS
438	459	8/5/2004	SWS
438	461	8/5/2004	SWS
438	464	8/5/2004	SWS
438	465	8/5/2004	SWS
438	977	8/5/2004	SWS
29	740	8/5/2004	SWS
29	743	8/5/2004	SWS
156	584	8/5/2004	SWS
Updated	Above	1/13/2005	SWS

S.W.S.

S.W.S.

INTERFERENCE SEARCHED

Class	Subclass	Date	Examiner

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Key Words: Tape - Protective, Dicing, Wafer, Release; DBG -Dice Before Grinding;	8/5/2004	S.W.S. SWS
Die Pad; Chip Pad; Lead Frame; Wiring Substrate; Solder Balls, Bumps; Adhesion - UV, Ultraviolet, Thermal Degradation.	8/5/2004	S.W.S. SWS
Updated Above Search	1/13/2005	S.W.S. SWS
Search Tools - EAST (attached): USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB	8/5/2004 1-13-05	SWS S.W.S.